1-826469-3 ACTIVE

AMPMODU | AMPMODU Headers

TE Internal #: 1-826469-3

PCB Mount Header, Vertical, Board-to-Board, 26 Position, 2.54 mm [.1 in] Centerline, Partially Shrouded, Gold, Through Hole - Solder,

AMPMODU Headers

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Connectors > PCB Connectors > PCB Headers & Receptacles



PCB Connector Assembly Type: PCB Mount Header

PCB Mount Orientation: Vertical
Connector System: Board-to-Board

Number of Positions: 26

Number of Rows: 2

Features

Product Type Features

PCB Connector Assembly Type	PCB Mount Header
Connector System	Board-to-Board
Header Type	Partially Shrouded
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board

Configuration Features

Connector Contact Load Condition	Fully Loaded
PCB Mount Orientation	Vertical
Number of Positions	26
Number of Rows	2
Board-to-Board Configuration	Parallel

Body Features

Connector Profile	Standard
Primary Product Color	Black

Contact Features

PCB Contact Termination Area Plating Material Thickness	3 – 5 µm
Contact Shape & Form	Round
Contact Underplating Material	Nickel



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PCB Contact Termination Area Plating Material	Tin
Contact Base Material	Copper Zinc
Contact Mating Area Plating Material	Gold
Contact Type	Pin
Contact Current Rating (Max)	5 A
Termination Features	
Termination Method to Printed Circuit Board	Through Hole - Solder
Mechanical Attachment	
Mating Alignment	With
Mating Alignment Type	Polarization
PCB Mount Retention	Without
PCB Mount Alignment	Without
Connector Mounting Type	Board Mount
Housing Features	
Centerline (Pitch)	2.54 mm[.1 in]
Housing Material	PCT
Dimensions	
Row-to-Row Spacing	2.54 mm[.1 in]
PCB Thickness (Recommended)	1.57 mm[.062 in]
Usage Conditions	
Housing Temperature Rating	High
Operating Temperature Range	-65 – 105 °C[-85 – 221 °F]
Operation/Application	
Circuit Application	Signal
Industry Standards	
UL Flammability Rating	UL 94V-0
Packaging Features	
Packaging Type	Box

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU Compliant
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EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JUNE 2023 (235) Does not contain REACH SVHC
Halogen Content	Not Low Halogen - contains Br or Cl > 900 ppm.
Solder Process Capability	Pin-in-Paste capable to 260°C

Product Compliance Disclaimer

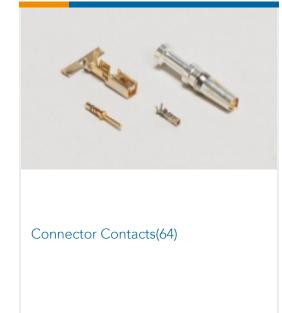
This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts



Also in the Series | AMPMODU Headers



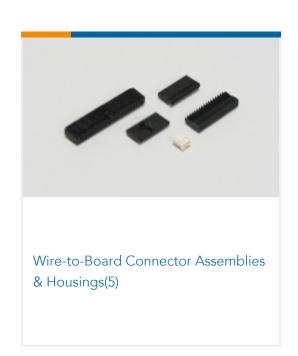




Connector Hardware(2)







Customers Also Bought







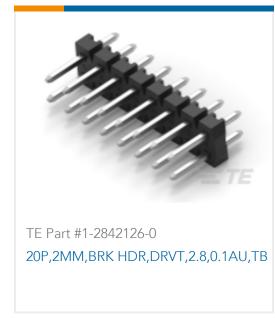




2X5P MOD II SHROUDED HEADER, ST









Documents

Product Drawings

2X13P MOD II SHROUDED HEADER, ST

English

CAD Files

3D PDF

3D

Customer View Model

ENG_CVM_CVM_1-826469-3_E.2d_dxf.zip

PCB Mount Header, Vertical, Board-to-Board, 26 Position, 2.54 mm [.1 in] Centerline, Partially Shrouded, Gold, Through Hole - Solder, AMPMODU Headers



English

Customer View Model

ENG_CVM_CVM_1-826469-3_E.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_1-826469-3_E.3d_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Agency Approvals

UL Report

English